

Title (en)
TITANIUM COPPER FOR ELECTRONIC COMPONENTS

Title (de)
TITANKUPFER FÜR ELEKTRONISCHE KOMPONENTEN

Title (fr)
TITANE-CUIVRE POUR COMPOSANTS ÉLECTRONIQUES

Publication
EP 3460081 B1 20200513 (EN)

Application
EP 18196022 A 20180921

Priority
JP 2017182738 A 20170922

Abstract (en)
[origin: EP3460081A2] The present invention is intended to improve bending workability of titanium copper for electronic components, and to provide a titanium copper for electronic components, which has excellent bending workability even when subjected to beating process, and to provide a method for manufacturing the same. One embodiment of the present invention is a titanium copper, comprising 2.0 to 4.5 mass% of Ti, and at least one element selected from the group consisting of Fe, Co, Ni, Cr, Zn, Zr, P, B, Mo, V, Nb, Mn, Mg, and Si in total of 0 to 0.5 mass% as a third element(s), and the rest consisting of copper and inevitable impurities, wherein in a crystal orientation analysis by EBSD measurement on the rolled surface, when an orientation difference of 5° or more is defined as a crystal grain boundary, a coefficient of variation of crystal grain size is 45% or less, and an area ratio of Cube orientation {001} <100> is 5% or less.

IPC 8 full level
C22C 9/00 (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP RU)
C22C 9/00 (2013.01 - EP RU); **C22F 1/08** (2013.01 - EP RU); **H01B 1/02** (2013.01 - RU); **H01B 1/026** (2013.01 - EP); **C22F 1/02** (2013.01 - EP)

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
EP 3460081 A2 20190327; **EP 3460081 A3 20190515**; **EP 3460081 B1 20200513**; JP 2019056166 A 20190411; JP 6310130 B1 20180411; RU 2691007 C1 20190607

DOCDB simple family (application)
EP 18196022 A 20180921; JP 2017182738 A 20170922; RU 2018133244 A 20180920